

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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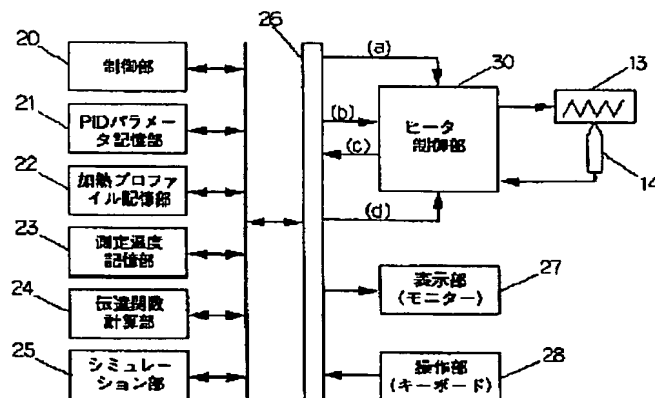
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INT.CL. : H01L 21/60 H01L 21/603

TITLE : THERMOCOMPRESSION BONDER  
FOR WORK AND  
THERMOCOMPRESSION BONDING  
FOR THE WORK



ABSTRACT : PROBLEM TO BE SOLVED: To provide a thermocompression bonder for works and a method of thermocompression-bonding works, through which at PID parameters setting is reduced and thus a heater is not damaged during the setting of the parameters.

SOLUTION: In a thermocompression bonder for effecting temperature control at the time of bonding by causing a heater control section 30 to PID-control the supply of power to a heater 13, a transfer function that identifies the heater, including a power supply section and a temperature detection section is calculated by a transfer function calculating section 24, based on actual temperature increasing data. To set PID parameters for implementing a predetermined heating profile, temperature changes are calculated by a simulation section 25 using the transfer function, and the calculated result is displayed graphically on a display section 27, together with the heating profile. As a result, the PID parameters can be set quickly with a smaller number of trials by simulating the temperature changes of the heater 13, without actually supplying power to the heater 13.

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